

SPW20N60CFD

650

0.22

20.7

PG-TO247

Ω

V_{DS} @ T_{imax}

R_{DS(on)}

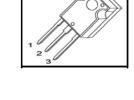
 I_{D}

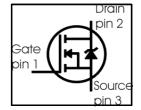
Cool MOS™ Power Transistor

Feature

- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- Intrinsic fast-recovery body diode
- Extreme low reverse recovery charge
- Pb-free lead plating; RoHS compliant; Halogen free mold compound
- Qualified for industrial grade applications according to JEDEC⁰⁾

Туре	Package	Ordering Code	Marking
SPW20N60CFD	PG-TO247	Q67040-S4617	20N60CFD





Maximum Ratings

Parameter	Symbol	Value	Unit
Continuous drain current	⊿		Α
T _C = 25 °C		20.7	
T _C = 100 °C		13.1	
Pulsed drain current, t_p limited by T_{jmax}	I _{D puls}	52	
Avalanche energy, single pulse	EAS	690	mJ
$I_{\rm D} = 10 \text{ A}, V_{\rm DD} = 50 \text{ V}$			
Avalanche energy, repetitive t_{AR} limited by T_{jmax} 1)	E _{AR}	1	\Box
$I_{\rm D} = 20 \text{ A}, \ V_{\rm DD} = 50 \text{ V}$			
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I _{AR}	20	Α
Reverse diode d <i>v</i> /d <i>t</i>	d <i>v</i> /d <i>t</i>	40	V/ns
I _S =20.7A, V _{DS} =480V, T _j =125°C			
Gate source voltage	V_{GS}	±20	V
Gate source voltage AC (f >1Hz)	V_{GS}	±30	
Power dissipation, $T_C = 25^{\circ}C$	P _{tot}	208	W
Operating and storage temperature	$T_{\rm j}$, $T_{ m stg}$	-55 +150	°C





Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope	d <i>v</i> /d <i>t</i>	80	V/ns
$V_{\rm DS}$ = 480 V, $I_{\rm D}$ = 20.7 A, $T_{\rm j}$ = 125 °C			
Maximum diode commutation speed	d <i>i≓</i> dt	900	A/µs
$V_{\rm DS}$ = 480 V, $I_{\rm D}$ = 20.7 A, $T_{\rm j}$ = 125 °C			

Thermal Characteristics

Parameter	Symbol		Values	i	Unit
		min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	-	-	0.6	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
Soldering temperature, wavesoldering	T_{sold}	-	-	260	°C
1.6 mm (0.063 in.) from case for 10s					

Electrical Characteristics, at Tj=25°C unless otherwise specified

Parameter	Symbol	Conditions		Values		Unit
			min. typ.		max.	
Drain-source breakdown voltage	V _{(BR)DSS}	VGS=0V, /D=0.25mA	600	-	ľ	V
Drain-Source avalanche	V _{(BR)DS}	V _{GS} =0V, I _D =20A	-	700	-	
breakdown voltage						
Gate threshold voltage	V _{GS(th)}	/D=1000μA, VGS=VDS	3	4	5	
Zero gate voltage drain current	IDSS	V _{DS} =600V, V _{GS} =0V,				μA
		<i>T</i> j=25°C,	-	2.1	-	
		<i>T</i> j=150°C	-	1700	-	
Gate-source leakage current	l _{GSS}	V _{GS} =20V, V _{DS} =0V	-	1	100	nA
Drain-source on-state resistance	R _{DS(on)}	VGS=10V, ID=13.1A,				Ω
		<i>T</i> j=25°C	-	0.19	0.22	
		<i>T</i> j=150°C	-	0.51	-	
Gate input resistance	R _G	f=1MHz, open Drain	-	0.54	-	





Electrical Characteristics, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions		Values		Unit
			min.	typ.	max.	
Transconductance	g_{fs}	V _{DS} ≥2*/ _D *R _{DS} (on)max, I _D =13.1A	ı	17.5	ı	s
Input capacitance	Ciss	V _{GS} =0V, V _{DS} =25V,	•	2400	ı	pF
Output capacitance	Coss	<i>f</i> =1MHz	•	780	•	
Reverse transfer capacitance	Crss		-	50	-	
Effective output capacitance,2) energy related	C _{o(er)}	V _{GS} =0V, V _{DS} =0V to 480V	-	83	-	pF
Effective output capacitance,3) time related	C _{o(tr)}		ı	160	1	
Turn-on delay time	t _{d(on)}	V _{DD} =380V, V _{GS} =0/10V,	-	12	-	ns
Rise time	t_{Γ}	/ _D =20.7A, <i>R</i> _G =3.6Ω		15	_	
Turn-off delay time	t _{d(off)}		-	59	-	
Fall time	t _f		-	6.4	-	

Gate Charge Characteristics

Gate to source charge	Q _{gs}	V _{DD} =480V, I _D =20.7A	-	15	-	nC
Gate to drain charge	Q_{gd}		-	54	-	
Gate charge total	Qg	V _{DD} =480V, I _D =20.7A,	-	95	124	
		V _{GS} =0 to 10V				
Gate plateau voltage	V _(plateau)	V _{DD} =480V, I _D =20.7A	-	7	-	V

⁰J-STD20 and JESD22

¹Repetitve avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR} * f$.

 $^{^2}C_{0(er)}$ is a fixed capacitance that gives the same stored energy as C_{0ss} while V_{DS} is rising from 0 to 80% V_{DSS} .

 $³C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

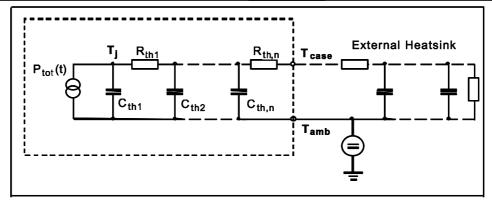


Electrical Characteristics, at T_i = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	Is	T _C =25°C	-	-	20.7	Α
Inverse diode direct current, pulsed	I _{SM}		-	-	52	
Inverse diode forward voltage	V_{SD}	VGS=0V, IF=IS	-	1	1.2	V
Reverse recovery time	t _{rr}	V _R =480V, I _F =I _S ,	-	150	-	ns
Reverse recovery charge	Q _{rr}	d <i>i</i> _F /d <i>t</i> =100A/µs	-	1	-	μC
Peak reverse recovery current	<i>I</i> rrm		-	13	-	Α
Peak rate of fall of reverse recovery current	di _{ri} /dt		-	1400	-	A/µs

Typical Transient Thermal Characteristics

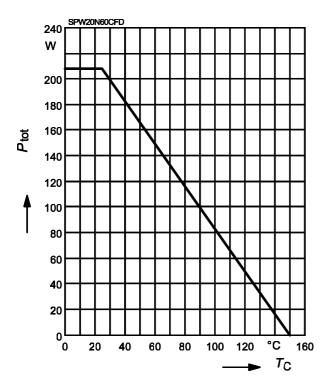
Symbol	Value	Unit	Symbol	Value	Unit
	typ.			typ.	
Thermal re	esistance	•	Thermal c	apacitance	•
R _{th1}	0.007686	K/W	C _{th1}	0.0003764	Ws/K
R _{th2}	0.015		C _{th2}	0.001412	
R _{th3}	0.029		C _{th3}	0.001932	
R _{th4}	0.114		C _{th4}	0.005299	
R _{th5}	0.136		C _{th5}	0.012	
R _{th6}	0.059		C _{th6}	0.091	





1 Power dissipation

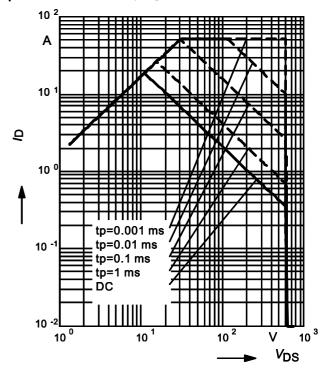
$$P_{\text{tot}} = f(T_{\text{C}})$$



2 Safe operating area

$$I_{D} = f(V_{DS})$$

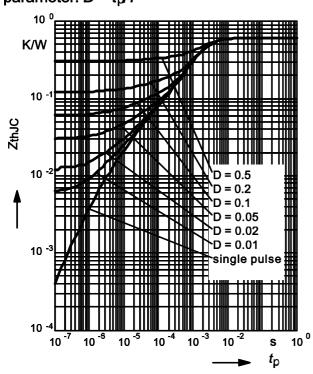
parameter : D = 0 , $T_C=25$ °C



3 Transient thermal impedance

$$Z_{\text{thJC}} = f(t_{\text{D}})$$

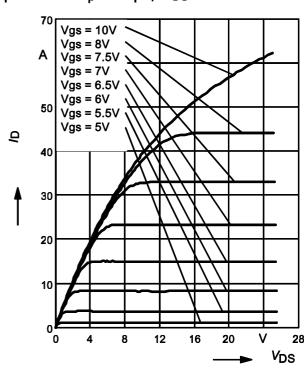
parameter: $D = t_p/T$



4 Typ. output characteristic

 $I_{D} = f(V_{DS}); T_{i}=25^{\circ}C$

parameter: t_p = 10 μ s, V_{GS}



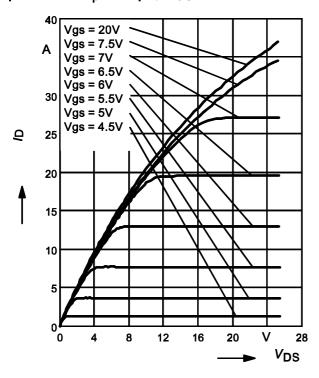
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5 Typ. output characteristic

 $I_{D} = f(V_{DS}); T_{j}=150^{\circ}C$

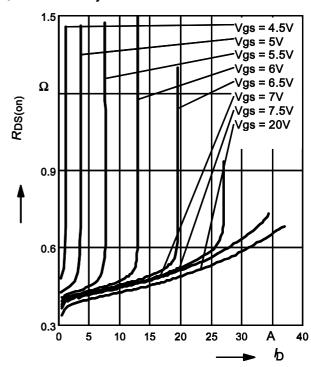
parameter: t_p = 10 μ s, V_{GS}



6 Typ. drain-source on resistance

 $R_{DS(on)}=f(I_D)$

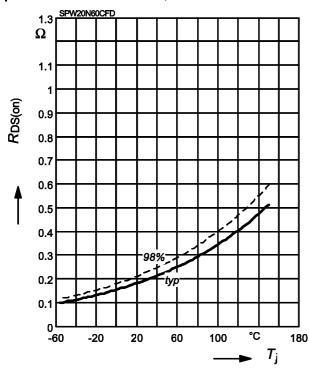
parameter: T_i=150°C, V_{GS}



7 Drain-source on-state resistance

 $R_{DS(on)} = f(T_i)$

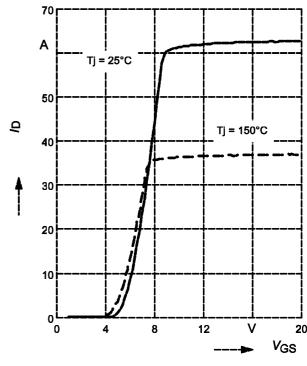
parameter : I_D = 13.1 A, V_{GS} = 10 V



8 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$

parameter: $t_p = 10 \mu s$



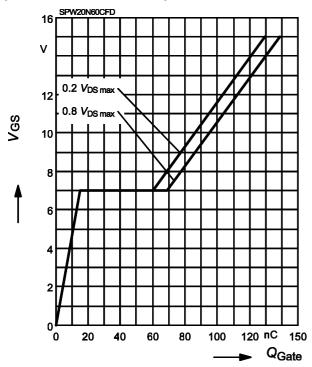
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9 Typ. gate charge

 $V_{GS} = f (Q_{Gate})$

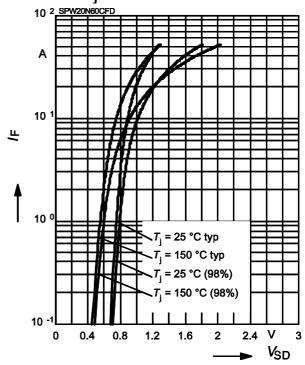
parameter: I_D = 20.7 A pulsed



10 Forward characteristics of body diode

 $I_{F} = f(V_{SD})$

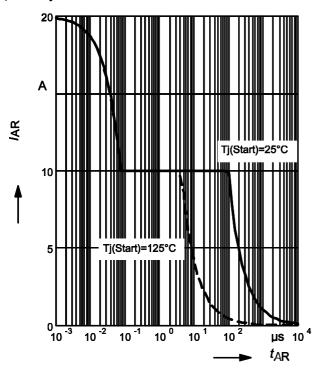
parameter: T_i , $t_p = 10 \mu s$



11 Avalanche SOA

 $I_{AR} = f(t_{AR})$

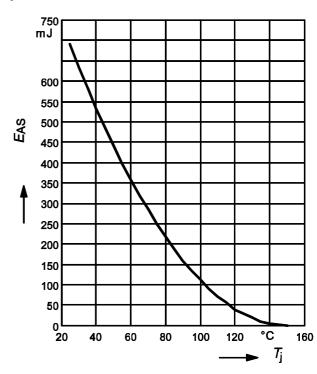
par.: *T*_j ≤ 150 °C



12 Avalanche energy

 $E_{AS} = f(T_j)$

par.: $I_D = 10 \text{ A}$, $V_{DD} = 50 \text{ V}$

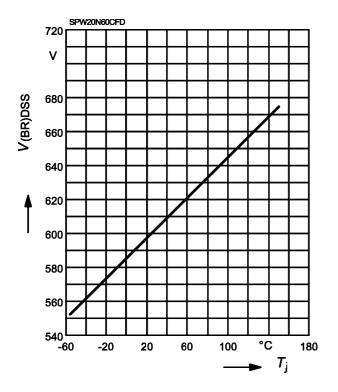


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13 Drain-source breakdown voltage

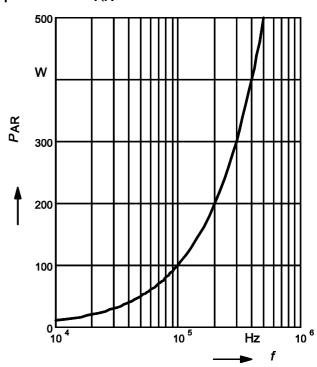
 $V_{(BR)DSS} = f(T_j)$



14 Avalanche power losses

 $P_{AR} = f(f)$

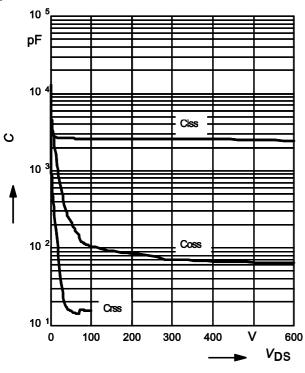
parameter: EAR=1mJ



15 Typ. capacitances

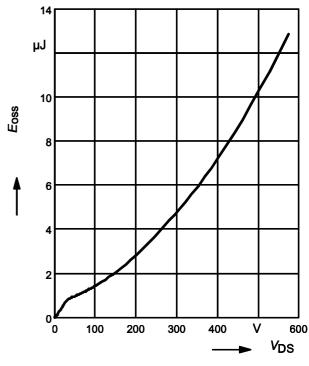
 $C = f(V_{DS})$

parameter: VGS=0V, f=1 MHz



16 Typ. $C_{\rm oss}$ stored energy

 $E_{oss} = f(V_{DS})$



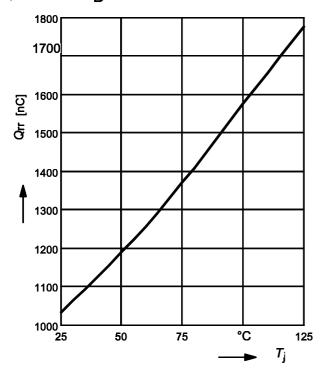
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17 Typ. reverse recovery charge

$$Q_{rr} = f(T_J)$$

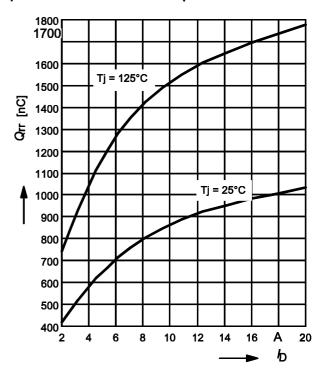
parameter: $I_D = 20.7A$



18 Typ. reverse recovery charge

$$Q_{rr} = f(I_D)$$

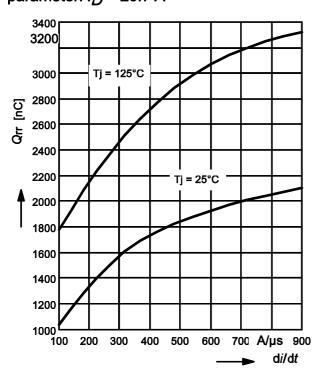
parameter: di/dt = 100 A/µs



19 Typ. reverse recovery charge

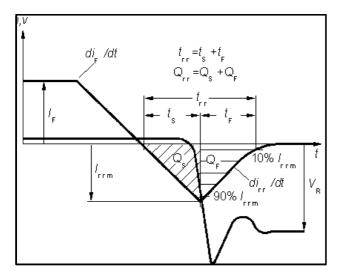
$$Q_{rr} = f(di/dt)$$

parameter: $I_D = 20.7 \text{ A}$



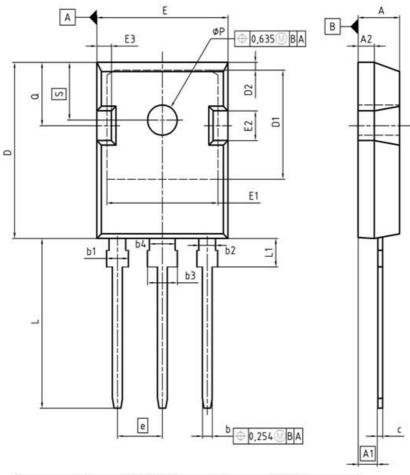


Definition of diodes switching characteristics

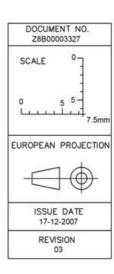




PG-TO-247-3-1



DIM	MILLIM	ETERS	INCH	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
Ь	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
С	0.55	0.68	0.022	0.027
D	20.82	21.10	0.820	0.831
D1	16.25	17.65	0.640	0.695
D2	1.05	1.35	0.041	0.053
Ε	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
e	5.	44	0.2	214
N	3	3		3
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248







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New package outlines TO-247

1 New package outlines TO-247

Assembly capacity extension for CoolMOSTM technology products assembled in lead-free package PG-TO247-3 at subcontractor ASE (Weihai) Inc., China (Changes are marked in blue.)

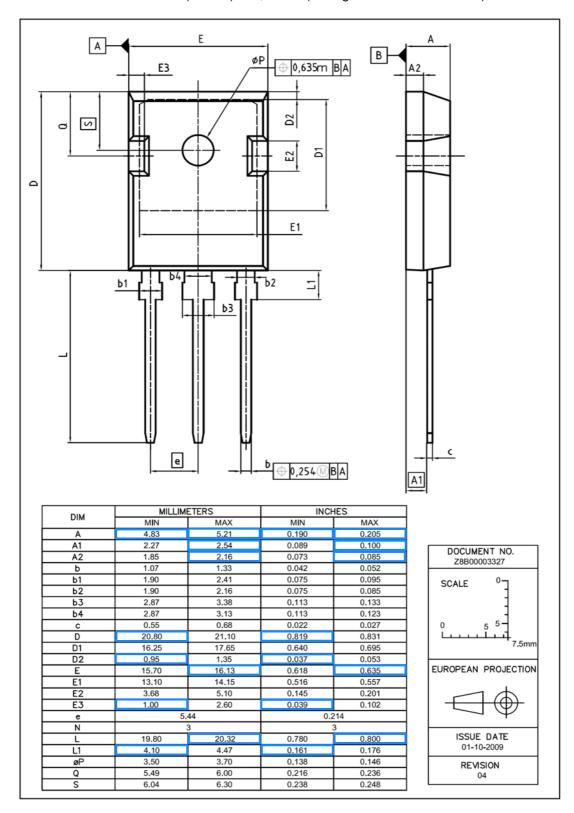


Figure 1 Outlines TO-247, dimensions in mm/inches

Final Data Sheet Erratum Rev. 2.0, 2010-02-01

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